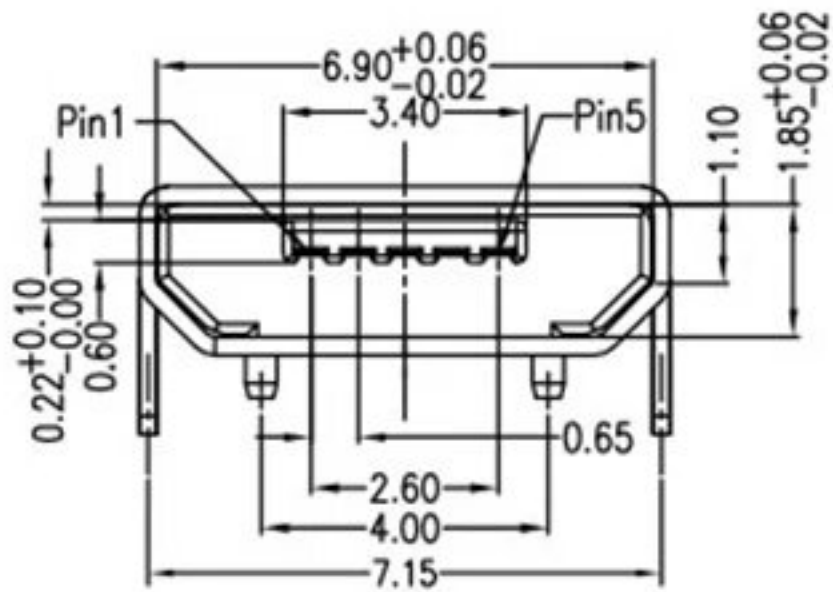
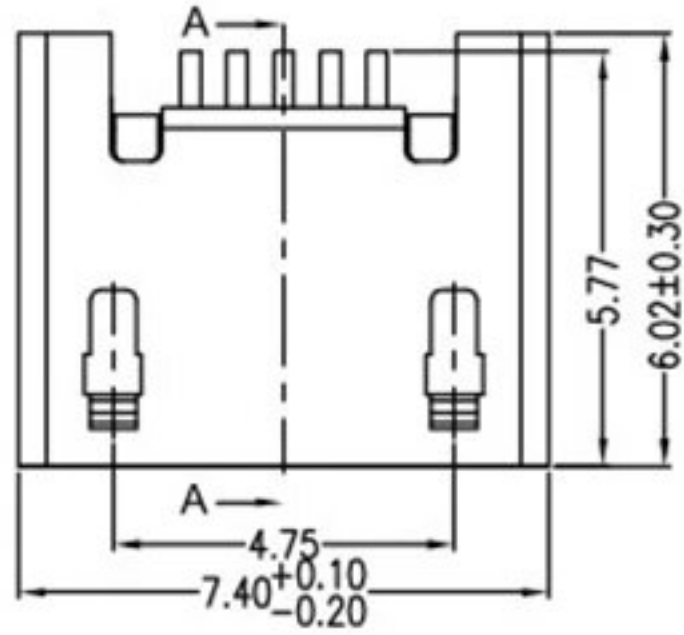
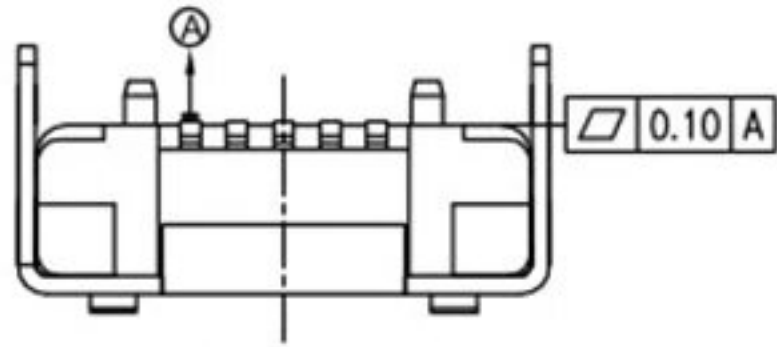
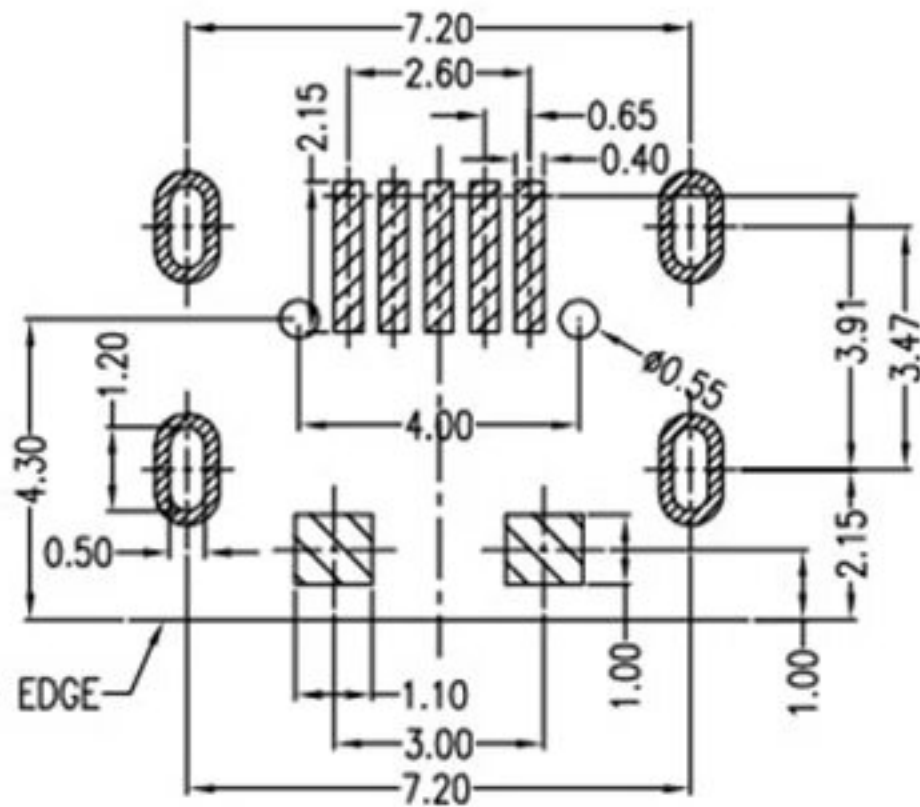
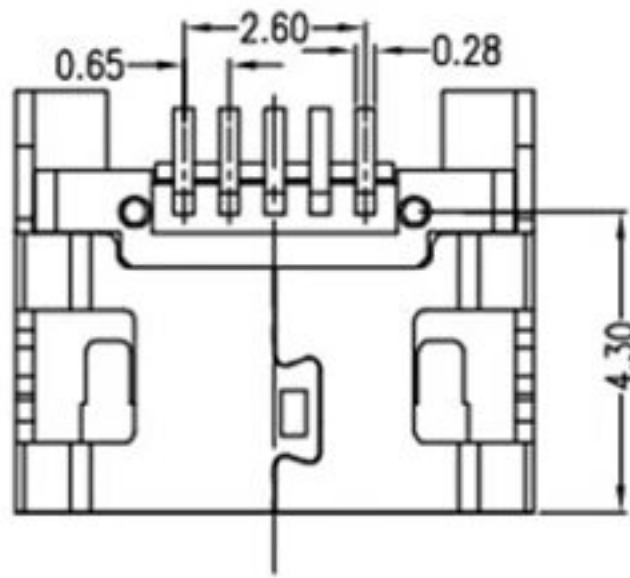
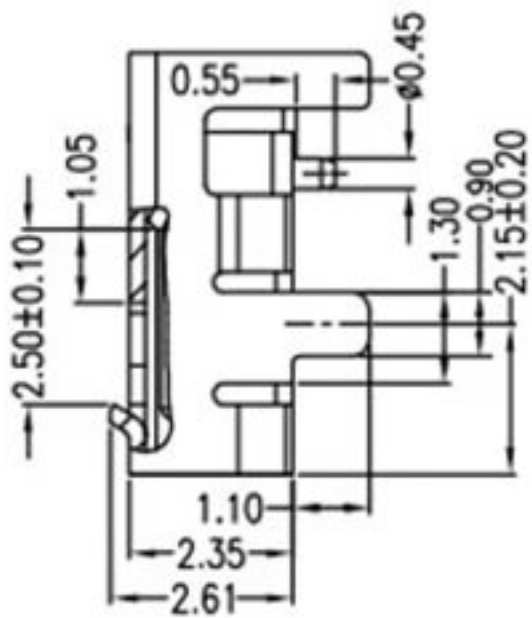


SECTION A-A





RECOMMENDED PCB LAYOUT

Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy,  $t=0.20\text{mm}$
- 1.3 Shell: copper alloy,  $t=0.25\text{mm}$

2. Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.0 Kgf Min.
- 2.7 Temperature range:  $-30^{\circ}\text{C}\sim 80^{\circ}\text{C}$